



DEFENSE LOGISTICS AGENCY
DEFENSE SUPPLY CENTER, COLUMBUS
3990 E. Broad Street
COLUMBUS, OH 43213-5000

IN REPLY
REFER TO DSCC-VQ-05-007217/Shing Yu/614-692-0588/mjg

February, 22 2005

SUBJECT: Level Q Assembly Certification, MIL-PRF-38535, FSC 5962

Mr. Zef Malik
President
Silicon Turnkey Solutions
400 Industrial Park Drive
Manteca, CA 95337

Dear Mr. Malik:

Silicon Turnkey Solutions (STS) has demonstrated to the Defense Supply Center, Columbus (DSCC) that it complies with MIL-PRF-38535, the performance specification used by the Department of Defense for monolithic integrated circuits.

STS is granted full Q level assembly certification, effective 26 January 2005, for the technology flows used for the quality assurance levels listed in the enclosure. This certification and listing includes the subcontractors approved by STS. This letter supersedes DSCC letter VQC-03-003114 to reflect the current certification status of STS as documented on the Quality Assurance Manual GCA22-001 Rev Y, dated August 30, 2004.

Testing must be performed using the facilities and methods listed in the Laboratory Suitability letter VQC-05-007218, or at facilities approved by the STS Technical Review Board using its MIL-PRF-38535 Quality Management Program Plan.

This certification is subject to the conditions in DoD 4120.24-M, Defense Standardization Program and SD-6.

Any and all of the facilities mentioned on the enclosure are subject to an audit by the qualifying activity at any time. The manufacturer shall be responsible for all audit expenses incurred for the offshore facilities. Offshore facilities are subject to all of the conditions of MIL-PRF-38535, Appendix E.

QPL/QML manufacturers shall notify the qualifying activity immediately after learning of a potential issuance of a GIDEP alert, problem advisory or major quality/reliability problem on their QPL/QML products. Failure to provide prior notification may be grounds for removal from QML-38535.

In addition, it is requested that the following activities be reported promptly to DSCC:

- ② Changes to certified facilities, process flows, or approved testing subcontractors
- ② Problem evaluation and a corrective action when the reliability of shipped parts is questionable
- ② Change of company QML contact or other key QML personnel

This certification is valid until terminated by written notice from the qualifying activity. If warranted, it may be withdrawn by this center at any time.

If you have any questions please contact Mr. Shing Yu at (614) 692-0588.

Sincerely,



ROBERT P. EVANS
Chief
Sourcing and Qualification Unit

ENCLOSURE

cc:

STS (Virginia Benguerel)

VQC (Scott Thomas)

VQC (Michael Grammens)

<u>OPERATION</u>	<u>TECHNOLOGY</u>	<u>FACILITY</u>	<u>LOCATION</u>
Assembly: <ul style="list-style-type: none"> • Die Attach • Wirebond • Seal 	Hermetic and Plastic Hermetic: JMI 7000, 84-1 LMI & LMISR4, 8360, QMI536, and 71-1 Plastic : 84-1 LMI, 8329A, 8361H, 8361J, 965-1L, 967-1, and 967-3 Gold Wire 1.0 – 1.3 mils Aluminum 1.0 – 1.25 mils Seam Weld and Solder Seal Molding Compound: 6600H, 6300HG, 6600CS, 6710, 7320CR, 7720S, and S372	STS Manteca	400 Industrial Dr. Manteca, CA 95337
Test:	As baselined by Lab Suitability information letter VQC-05-007218	STS Manteca STS Fremont	400 Industrial Dr. Manteca, CA 95337 43170 Osgood Rd. Fremont, CA 94539

Lead range for hermetic package families for the flows listed above include: Pre-J Leaded Chip Carrier (20-124), Leadless Chip Carrier (20-84), Flat Pack (40-352), PGA (64-176), and Side-Braze (8-64).

Lead range for plastic package families for the flows listed above include: EBGA (192-523 balls), MCM PBGA (72-288 balls), PBGA (192-1156 balls), PQFP (80-208), LQFP (64-144), PLCC (28-84), Plastic (28-68) and SOIC (8-16).